

[Title of Invention]

SEMICONDUCTOR MEMORY DEVICE

[Technical Field]

[0001]

5 Embodiments relate to a semiconductor memory device.

[Background Art]

[0002]

Semiconductor memory devices in which memory cells are three-dimensionally arranged are being developed. For example, a NAND nonvolatile memory device includes the multiple electrode layers stacked on a conductive layer, and a semiconductor film and a charge storage film provided in a memory hole extending through the multiple electrode layers; and memory cells are provided at the portions where the memory hole extends through the electrode layers. The memory capacity of such a memory device can be increased by increasing the layer number of electrode layers. However, as the layer number of the electrode layers increases, it becomes difficult to form the memory hole that extends through the multiple electrode layers.

[0003]

In contrast, a method can be used in which a first memory hole is formed to extend through multiple first electrode layers, and then, a second memory is formed to extend through multiple second electrode layers stacked on the first electrode layers so that the second memory hole communicates with the first memory hole. Although the difficulty is reduced thereby in the etching for forming a memory hole extending through the electrode layers stacked with the large layer number, there may be cases where a charge storage film formed in the first memory hole is subjected to the process damage due to the misalignment of the second memory hole.

[Prior Arts]

35 [Patent Documents]

[0004]

[Patent document 1] JP 2009-135324 A1

[Summary of Invention]

[Issue to be solved by the Invention]

[0005]

5 An embodiment provides a semiconductor memory device in which the charge storage film can be prevented from the process damage.

[Means for Solving the Issue]

[0006]

10 According to one embodiment, a semiconductor memory device includes multiple first electrode layers stacked in a first direction, multiple second electrode layers stacked in the first direction, a first columnar body extending through the multiple first electrode layers in the first direction, a second columnar
15 body extending through the multiple second electrode layers in the first direction, a connection part connecting the first columnar body and the second columnar body, and a spacer film having an island configuration surrounding the connection part. The multiple first electrode layers and the multiple
20 second electrode layers are arranged in the first direction, and the connection part and the spacer film are provided between the multiple first electrode layers and the multiple second electrode layers.

[Brief Descriptions of Drawings]

25 [0007]

FIG. 1 is a perspective view schematically showing a memory device 1 according to a first embodiment;

FIG. 2 is a schematic cross-sectional view showing the memory device according to the first embodiment;

30 FIGS. 3A to 10 are schematic cross-sectional views showing manufacturing processes of the memory device according to the first embodiment;

FIGS. 11A and 11B are schematic cross-sectional views showing a characteristic of the memory device according to the
35 first embodiment;

FIG. 12 is a schematic cross-sectional view showing a

memory device according to a second embodiment;

FIGS. 13A to 14B are schematic cross-sectional views showing manufacturing processes of the memory device according to the second embodiment;

5 FIGS. 15A and 15B are schematic cross-sectional views showing characteristics of the memory device according to the second embodiment;

10 FIG. 16 is a schematic cross-sectional view showing a memory device according to a modification of the second embodiment;

FIG. 17 is a schematic cross-sectional view showing a memory device according to a third embodiment;

15 FIGS. 18A to 19B are schematic cross-sectional views showing manufacturing processes of the memory device according to the third embodiment;

FIG. 20 is a schematic cross-sectional view showing a memory device according to a fourth embodiment;

20 FIGS. 21A to 22B are schematic cross-sectional views showing manufacturing processes of the memory device according to the fourth embodiment;

FIG. 23 is a schematic cross-sectional view showing a memory device according to a modification of the fourth embodiment;

25 FIGS. 24A to 26B are schematic views showing manufacturing processes of the memory device according to the modification of the fourth embodiment;

FIG. 27 is a schematic cross-sectional view showing a manufacturing process of the memory device according to the modification of the fourth embodiment; and

30 FIG. 28 is a schematic plan view showing a memory device according to another modification of the fourth embodiment.

[Description of Embodiments]

[0008]

35 Embodiments will now be described with reference to the drawings. The same portions inside the drawings are marked

with the same numerals; a detailed description is omitted as appropriate; and the different portions are described. The drawings are schematic and conceptual; and the relationships between the thicknesses and widths of portions, the proportions of sizes among portions, etc., are not necessarily the same as the actual values. Also, the dimensions and/or the ratios may be illustrated differently between the drawings, even in the case where the same portion is illustrated.

[0009]

Also, the dispositions and the configurations of the portions are described using an X-axis, a Y-axis, and a Z-axis shown in the drawings. The X-axis, the Y-axis, and the Z-axis are orthogonal to each other and respectively refer to an X-direction, a Y-direction, and a Z-direction. Also, there are cases where the Z-direction is described as upward, and the reverse direction thereof is described as downward.

[0010]

(First embodiment)

FIG. 1 is a perspective view schematically showing a memory device 1 according to a first embodiment. The memory device 1 is, for example, a NAND flash memory device that includes three-dimensionally arranged memory cells. The insulating films are not illustrated in FIG. 1 to show the structure of the memory device 1.

[0011]

As shown in FIG. 1, the memory device 1 includes multiple first electrode layers (hereinbelow, a select gate SGS and a word line WL1), multiple second electrode layers (hereinbelow, a word line WL2 and a select gate SGD), a columnar body PB1, and a columnar body PB2.

[0012]

For example, the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD are stacked on a source layer SL. The source layer SL is, for example, a P-type well provided in a silicon substrate (not illustrated). Also, the source layer SL may be a metal layer or a polysilicon layer

provided on a silicon substrate with an inter-layer insulating film (not illustrated) interposed.

[0013]

5 The first columnar body PB1 extends in the stacking direction (the Z-direction) through the select gate SGS and the word line WL1. The second columnar body PB2 extends in the Z-direction through the word line WL2 and the select gate SGD.

[0014]

10 The memory device 1 further includes a spacer film 20 and a bit line BL. The spacer film 20 is provided in an island configuration to surround a connection part JP between the columnar body PB1 and the columnar body PB2 (referring to FIG. 2). In other words, the spacer film 20 is provided between the first columnar body PB1 and the second columnar
15 body PB2, and is provided apart from another spacer film 20 that is provided between another first columnar body PB1 and another second columnar body PB2. For example, the spacer films 20 that are adjacent to each other in the X-direction and the Y-direction are provided apart from each other. The bit
20 line BL is electrically connected to a semiconductor film SF included in the columnar body PB2 (referring to FIG. 2) via a connection plug VB.

[0015]

25 FIG. 2 is a schematic cross-sectional view showing the memory device 1 according to the first embodiment. The cross-sectional structure of the columnar bodies PB1 and PB2 and the connection part JP is shown in FIG. 2.

[0016]

30 As shown in FIG. 2, the memory device 1 includes a memory film MF, the semiconductor film SF, and an insulating core CA. The memory film MF, the semiconductor film SF, and the insulating core CA extend in the Z-direction through the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD. For example, when the memory film MF,
35 the semiconductor film SF, and the insulating core CA are regarded as a continuous body, the columnar body PB1 is a

portion lower than the connection part JP, and the columnar body PB2 is a portion higher than the connection part JP.

[0017]

5 The insulating core CA is, for example, silicon oxide extending in the Z-direction. The semiconductor film SF is, for example, a polysilicon film provided to cover the insulating core CA. The semiconductor film SF contacts the source layer SL and is electrically connected to the source layer SL at the bottom of the columnar body PB1.

10 [0018]

The memory film MF is provided to cover the side surface of the semiconductor film SF. The memory film MF is an insulating film that has a charge storage function. For example, memory cells MC are provided at the portions where the columnar body PB1 crosses the word lines WL1 and the portions where the columnar body PB2 crosses the word lines WL2. The memory film MF is provided between the semiconductor film SF and the word lines WL1 and between the semiconductor film SF and the word lines WL2. The memory film MF includes portions serving respectively as charge storage portions of the memory cells MC. Alternatively, the memory film MF may have a floating gate structure in which an insulating film surrounds a conductive film.

[0019]

25 The memory device 1 includes inter-layer insulating films 13, 15, 23, and 25. The inter-layer insulating film 13 is provided between the source layer SL and the select gate SGS. The inter-layer insulating films 15 are provided between the word lines WL1 adjacent to each other in the Z-direction. The inter-layer insulating film 23 is provided between the word line WL1 and the word line WL2 and surrounds the spacer film 20. The inter-layer insulating films 25 are provided between the word lines WL2 adjacent to each other in the Z-direction.

[0020]

35 As shown in FIG. 2, the spacer film 20 is provided to surround the connection part JP between the columnar body

PB1 and the columnar body PB2. For example, a width WS1 in the X-direction of the spacer film 20 is greater than a width WT1 of the first columnar body PB1 at a portion thereof extending through the word line WL1. Also, a minimum width WJ1 in the X-direction of the connection part JP is less than the width WT1 of the columnar body PB1 at the portion extending through the word line WL1. Here, the width WT1 of the columnar body PB1 is the width of the columnar body PB1 at the portion thereof extending through the word line WL1 that is most proximate to the connection part JP among the multiple word lines WL1.

[0021]

Also, the minimum width WJ1 of the connection part JP is less than a width WB1 of the columnar body PB1. The width WB1 of the columnar body PB1 is, for example, the width of a portion extending through the select gate SGS or the word line WL1 most proximate to the lower end of the columnar body PB1. In the example, the width WB1 is the width thereof at a portion extending through the select gate SGS.

[0022]

For example, when the X-Y cross sections of the columnar body PB1 and the connection part JP are substantially circular, the outer diameter WJ1 of the connection part JP is less than the outer diameter WT1 and the outer diameter WB1 of the columnar body PB1.

[0023]

A method for manufacturing the memory device 1 according to the first embodiment will now be described with reference to FIGS. 3 to 10. FIGS. 3A to 6B, FIG. 7, FIG. 8A, FIG. 8B, FIG. 9, and FIG. 10 are schematic cross-sectional views showing manufacturing processes of the memory device 1.

[0024]

As shown in FIG. 3A, the inter-layer insulating films 13, 15, and 23 and a sacrificial film 17 are stacked on the source layer SL. The inter-layer insulating films 15 and the sacrificial

film 17 are alternately stacked on the inter-layer insulating film 13. The inter-layer insulating film 23 is formed on the sacrificial film 17T that is provided at the top of the multiple sacrificial films 17. The inter-layer insulating films 13, 15, and 23 are, for example,
5 silicon oxide films. The sacrificial films 17 are, for example, silicon nitride films.

[0025]

Continuing, a memory hole MH1 is formed with a depth reaching the source layer SL from the upper surface of the inter-layer insulating film 23. For example, the memory hole MH1 is
10 formed by selectively removing the inter-layer insulating films 13, 15, and 23 and the sacrificial films 17 by using RIE (Reactive Ion Etching).

[0026]

As shown in FIG. 3B, a sacrificial film 33 is formed to fill the memory hole MH1. The sacrificial film 33 is, for example, an amorphous silicon film formed using CVD (Chemical Vapor
15 Deposition).

[0027]

As shown in FIG. 4A, a recess portion RC is formed in the upper portion of the memory hole MH1 by etching back the sacrificial film 33. The recess portion RC is formed so that the bottom surface of the recess portion RC is positioned at a higher level than the sacrificial film 17T. The sacrificial film 17T is
20 provided at the top position of the multiple sacrificial films 17 stacked in the Z-direction.

[0028]

As shown in FIG. 4B, for example, the recess portion RC is enlarged in the lateral direction by the etching of the inter-layer insulating film 23 using isotropic dry etching. That is, the width of
30 the recess portion RC is made greater than the width of the memory hole MH1. For example, when the X-Y cross section of the memory hole MH1 is substantially circular, the center of the recess portion RC matches the center of the memory hole MH1.

[0029]

As shown in FIG. 5A, the spacer film 20 is formed to cover the inner surface of the recess portion RC. The spacer film 20 includes a material different from the sacrificial film 33. The spacer film 20 may include, for example, silicon oxide (SiO₂), aluminum oxide (Al₂O₃), hafnium oxide (HfO) or silicon nitride (SiN). The spacer film 20 may be polysilicon or amorphous silicon to which an impurity is added, or silicon carbide (SiC).

[0030]

As shown in FIG. 5B, the spacer film 20 is etched back so that a portion thereof contacting the inner wall of the recess portion RC remains. For example, the portions thereof that are deposited on the upper surface of the inter-layer insulating film 23 and on the sacrificial film 33 are removed using anisotropic RIE. Thereby, for example, the spacer film 20 remains, which has a ring configuration along the inner wall of the recessed portion RC.

[0031]

A thickness T_s of the spacer film 20 deposited on the inter-layer insulating film 23 (referring to FIG. 5A) is set so that a space remains inside the recess portion RC and, after the etching of the spacer film 20, a minimum width WJ2 of the recess portion RC is less than a width WT2 and a width WB2 of the memory hole MH1. Here, when the X-Y cross section of the memory hole MH1 is substantially circular, the minimum width WJ2 is the inner diameter of the ring-shaped spacer film 20. Also, the width WT2 of the memory hole MH1 is the inner diameter thereof at the portion extending through the sacrificial film 17T, and the width WB2 is the inner diameter thereof at a portion extending through the sacrificial film 17B that is provided at a position most proximate to the bottom surface of the memory hole MH1.

[0032]

As shown in FIG. 6A, a sacrificial film 35 is formed to fill the recess portion RC. The sacrificial film 35 is, for example, an amorphous silicon film.

[0033]

As shown in FIG. 6B, the sacrificial film 35 is polished using, for example, CMP (Chemical Mechanical Polishing) to expose the inter-layer insulating film 23. Thereby, the
 5 sacrificial film 35 can be removed so that a portion of the sacrificial film 35 remains which fills the recess portion RC.

[0034]

As shown in FIG. 7, the inter-layer insulating films 25 and sacrificial films 27 are stacked alternately on the inter-layer
 10 insulating film 23 and the sacrificial film 35. The inter-layer insulating films 25 are, for example, silicon oxide films, and the sacrificial films 27 are, for example, silicon nitride films. Also, a memory hole MH2 that communicates with the sacrificial film 35 is formed from the upper surface of an inter-layer insulating
 15 film 25T provided at the top position of the multiple inter-layer insulating films 25.

[0035]

As shown in FIG. 8A, the sacrificial film 35 and the sacrificial film 33 are selectively removed via the memory hole
 20 MH2 to form a memory hole MH in which the memory hole MH1 and the memory hole MH2 are joined together. Subsequently, the memory film MF is formed on the inner surface of the memory hole MH.

[0036]

25 Thus, when the number of stacks of the word lines WL is large, it is preferable to form the memory hole MH1 and the memory hole MH2 separately so as to finally form one memory hole MH. Thereby, the difficulty can be reduced in the etching process, etc., when forming the memory hole MH extending
 30 through the large number of word lines WL.

[0037]

FIG. 8B is a schematic view showing an X-Y cross section of the memory hole MH. As shown in FIG. 8B, the memory film MF has a structure in which a blocking insulating film FL1, a
 35 charge storage film FL2, and a tunnel insulating film FL3 are stacked in order on the inner surface of the memory hole MH.

The blocking insulating film FL1 and the tunnel insulating film FL3 are, for example, silicon oxide films. The charge storage film FL2 is, for example, a silicon nitride film. The blocking insulating film FL1 may include, for example, a metal oxide.

5 [0038]

As shown in FIG. 9, a portion of the memory film MF is selectively removed, which is formed on the source layer SL at the bottom surface of the memory hole MH. For example, the memory film MF is selectively removed using anisotropic RIE.

10 [0039]

As shown in FIG. 10, the semiconductor film SF is formed to cover the inner surface of the memory hole MH after the memory film MF is formed. The semiconductor film SF is, for example, a polysilicon film. The semiconductor film SF is formed to contact the memory film MF. Also, the semiconductor film SF contacts the source layer SL at the bottom of the memory hole MH.

[0040]

Moreover, the insulating core CA is formed to fill the interior of the memory hole MH. The insulating core CA is, for example, silicon oxide deposited using CVD. Then, the sacrificial films 17 and 25 are selectively removed, and the word lines WL1 and WL2 and the select gates SGS and SGD are formed by replacing the sacrificial films 17 and 25 with metal layers.

[0041]

FIGS. 11A and 11B are schematic cross-sectional views showing a characteristic of the memory device 1 according to the first embodiment. FIG. 11A is a schematic cross-sectional view showing the process of selectively removing the memory film MF in a memory device 2 according to a comparative example. FIG. 11B is a schematic cross-sectional view showing the process of selectively removing the memory film MF of the memory device 1.

35 [0042]

As shown in FIG. 11A, the spacer film 20 is not included

in the memory device 2. Also, as shown in FIG. 11A, the memory hole MH2 is misaligned with respect to the memory hole MH1.

[0043]

5 As shown in FIG. 11A, the inner wall of the memory hole MH1 has a portion exposed via the memory hole MH2 due to the misalignment of the memory hole MH2. In such a case, when the portion of the memory film MF that is formed on the source layer SL is removed by RIE at the opening side of the memory
10 hole MH2, a portion of the inner wall is subjected to ion bombardment in the memory hole MH1. Therefore, a damage region is partially formed in the memory film MF that is formed on the inner wall of the memory hole MH1. As a result, there may be some defects in the memory cells MC such as
15 degradation of the charge storage characteristics, an increase of the leakage current, etc.

[0044]

In contrast, as shown in FIG. 11B, the memory device 1 has a configuration in which the inner wall of the memory hole
20 MH1 is shielded by the spacer film 20 and cannot be viewed from the opening side of the memory hole MH2. Therefore, the memory film that is formed on the inner wall of the memory hole MH1 is protected by the spacer film 20 when removing the portion of the memory film MF on the source layer SL.
25 Although the memory film MF includes a portion formed on the surface of the spacer film 20, which is damaged by the ion bombardment, the portion of the memory film MF provided on the spacer film 20 is electrically isolated and does not affect on the operation of the memory device 1.

30 [0045]

Thus, in the memory device 1 according to the embodiment, the memory film MF formed on the inner wall of the memory hole MH1 can be protected, and the degradation of the characteristics of the memory cells MC can be prevented by
35 providing the spacer film 20 at the connection portion between the memory hole MH1 and the memory hole MH2.

[0046]

Moreover, as shown in FIG. 11B, the width of the opening that links the memory hole MH1 and the memory hole MH2 becomes narrow when the memory hole MH2 is misaligned with respect to the memory hole MH1. Thus, there may be a case where the communication between the memory hole MH1 and the memory hole MH2 is blocked in the process of forming the memory film MF and the semiconductor film SF on the inner surface of the memory hole MH (referring to FIG. 10).
Accordingly, it is preferable for the memory hole MH1 that the widths thereof in the X-direction and the Y-direction (e.g., the inner diameter) is greater than the widths in the X-direction and the Y-direction of the memory hole MH2. In other words, it is preferable for the columnar body PB1 that the widths thereof in the X-direction and the Y-direction (e.g., the outer diameter) is greater than the widths in the X-direction and the Y-direction of the columnar body PB2.

[0047]

(Second embodiment)

FIG. 12 is a schematic cross-sectional view showing a memory device 3 according to a second embodiment. The cross-sectional structure of the columnar bodies PB1 and PB2 is shown in FIG. 12.

[0048]

As shown in FIG. 12, the columnar body PB1 extends in the Z-direction and extends through the select gate SGS and the multiple word lines WL1 stacked in the Z-direction. The columnar body PB2 extends in the Z-direction and extends through the select gate SGD and the multiple word lines WL2 stacked in the Z-direction. The columnar body PB1 and the columnar body PB2 are connected between the word lines WLT1 and WLL2 which are positioned at the top of the multiple word lines WL1 and at the bottom of the multiple word lines WL2, respectively.

[0049]

As shown in FIG. 12, the columnar bodies PB1 and PB2

include the memory film MF, the semiconductor film SF, and the insulating core CA. The memory film MF, the semiconductor film SF, and the insulating core CA extend in the Z-direction through the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD. For example, the columnar bodies PB1 and PB2 are portions of a columnar body in which the memory film MF, the semiconductor film SF, and the insulating core CA are joined together. The columnar body PB1 is provided between the columnar body PB2 and the source layer SL. The semiconductor film SF is electrically connected to the source layer SL.

[0050]

As shown in FIG. 12, an inter-layer insulating film 15T and an insulating film 43 are provided between the word line WLT1 and the word line WLL2. The insulating film 43 is provided between the inter-layer insulating film 15T and the word line WLL2. The columnar body PB1 extends in the Z-direction through the inter-layer insulating film 15T and the insulating film 43. The inter-layer insulating film 15T and the insulating film 43 are, for example, silicon oxide films.

[0051]

A stopper film 40S is provided between the columnar body PB1 and the insulating film 43. For example, the stopper film 40S is provided to surround the columnar body PB1 in a cross section parallel to the upper surface of the word line WLT1 or the lower surface of the word line WLL2. For example, the stopper film 40S has a configuration in which the thickness in the Z-direction at a portion proximate to the columnar body PB1 is greater than the thickness in the Z-direction at a portion apart from the columnar body PB1. Moreover, the stopper film 40S has a lower surface contacting the inter-layer insulating film 15T. In the stopper film 40S, the width in the X-direction or the Y-direction of the lower surface is greater than the width in the X-direction or the Y-direction at the portion proximate to the word line WLL2.

[0052]

The stopper film 40S includes, for example, a material different from those of the inter-layer insulating film 15T, the insulating film 43, and the sacrificial film 27 described below. The stopper film 40S may include, for example, a metal oxide such as aluminum oxide (Al_2O_3), hafnium oxide (HfO) or the like. The stopper film 40S may include silicon carbide (SiC), etc. When the inter-layer insulating film 15T and the insulating film 43 include other than silicon oxide, the stopper film 40S may include silicon oxide (SiO_2). Also, when the sacrificial film 27 (described below) includes other than silicon nitride (SiN), the stopper film 40S may include silicon nitride.

[0053]

A method for manufacturing the memory device 3 according to the second embodiment will now be described with reference to FIGS. 13A to 14B. FIGS. 13A to 14B are schematic cross-sectional views showing manufacturing processes of the memory device 3 in order.

[0054]

For example, the multiple sacrificial films 17 are stacked on the source layer SL with the inter-layer insulating films 13 and 15 interposed. The inter-layer insulating film 13 is provided between the source layer SL and the sacrificial film 17 positioned at the bottom. The inter-layer insulating films 15 and the sacrificial films 17 are alternately stacked on the inter-layer insulating film 13. Then, the memory hole MH1 is formed with a depth to the source layer SL from the upper surface of the inter-layer insulating film 15T at the top position so that the memory hole MH1 reaches the source layer SL; subsequently, the sacrificial film 33 that fills the interior of the memory hole MH1 is formed (referring to FIGS. 3A and 3B).

[0055]

Also, as shown in FIG. 13A, the sacrificial film 33 and the inter-layer insulating film 15T are partially removed so that the upper end of the sacrificial film 33 protrudes to a higher level than the inter-layer insulating film 15T. For example, after the portion of the sacrificial film 33 deposited at a higher level than

the inter-layer insulating film 15T are selectively etched back, the inter-layer insulating film 15T is partially etched back.

[0056]

As shown in FIG. 13B, a stopper film 40 is formed on the inter-layer insulating film 15T. For example, the stopper film 40 is formed using CVD, and covers the upper end of the sacrificial film 33. For example, the sacrificial film 33 has the upper end (i.e., the portion protruding to the higher level than the inter-layer insulating film 15T) that has a width ΔT in the Z direction. The stopper film 40 has a thickness in the Z-direction about the same as the width ΔT .

[0057]

As shown in FIG. 13C, the stopper film 40 is etched back so that the portion thereof surrounding the upper end of the sacrificial film 33 remains. For example, the stopper film 40 is etched back using anisotropic RIE. Thereby, the stopper film 40S is formed around the upper end of the sacrificial film 33.

[0058]

As shown in FIG. 14A, the insulating film 43 is formed on the inter-layer insulating film 15T. The insulating film 43 is formed so that the upper surface of the sacrificial film 33 is exposed to the outside. For example, the insulating film 43 is formed to cover the sacrificial film 33 and the stopper film 40S by using CVD, and subsequently is partially removed using CMP or is subjected to etch-back. The surface of the insulating film 43 is planarized in which the upper surface of the sacrificial film 33 is exposed.

[0059]

As shown in FIG. 14B, the multiple sacrificial films 27 are stacked on the insulating film 43 with the inter-layer insulating films 25 interposed. Subsequently, the memory hole MH is formed with a depth reaching the source layer SL. The inter-layer insulating films 25 and the sacrificial films 27 are alternately stacked on the insulating film 43.

[0060]

The memory hole MH is formed by selectively removing

the sacrificial film 33 after forming the memory hole MH2 (referring to FIG. 15A). For example, the memory hole MH2 is formed with a depth reaching the sacrificial film 33 from the surface of the inter-layer insulating film 25T at the top position
5 by selectively removing the inter-layer insulating film 25 and the sacrificial film 27.

[0061]

Continuing, the memory film MF, the semiconductor film SF, and the insulating core CA are formed inside the memory
10 hole MH. Also, the word lines WL1 and WL2 and the select gates SGS and SGD are formed by selectively removing the sacrificial films 17 and 27 and replacing the sacrificial films 17 and 27 with metal layers.

[0062]

15 FIGS. 15A and 15B are schematic cross-sectional views showing characteristics of the memory device 3 according to the second embodiment. FIG. 15A is a schematic view showing a cross section of a stacked body including the sacrificial layers 17 and 27 after the memory hole MH2 is formed. FIG. 15B is a
20 schematic view showing the configuration of the memory hole MH2 when the stopper film 40S is not provided.

[0063]

The memory hole MH2 is formed to communicate with the sacrificial film 33. In many cases, the memory hole MH2 is
25 formed so that the bottom surface of the memory hole MH2 is at a position shifted in the X-direction or the Y-direction from a position matching the upper surface of the sacrificial film 33 due to the precision of the alignment in the manufacturing processes.

30 [0064]

In the memory device 3 according to the embodiment, the stopper film 40S and the upper surface of the sacrificial film 33 are exposed at the bottom surface of the memory hole MH2. The stopper film 40S is resistant to the etching conditions under
35 which the memory hole MH2 is formed. The stopper film 40S protects the inter-layer insulating film 15T and the sacrificial

films 17 provided below the stopper film 40S.

[0065]

In contrast, when the stopper film 40S is not provided, there may be cases where the inter-layer insulating film 15T exposed at the bottom surface of the memory hole MH2 is etched as shown in FIG. 15B, and the sacrificial films 17 also are etched which are provided below the inter-layer insulating film 15T. As a result, the unintentionally etching of the inter-layer insulating film 15T and the sacrificial films 17 forms a region EX.

[0066]

After the memory film MF is formed on the inner surface of the memory hole MH, in the process of selectively removing the portion of the memory film MF formed on the source layer SL, the portion thereof formed on the region EX also is etched or damaged (referring to FIG. 11A). Thereby, there may be cases where the semiconductor film SF and the word line WL1 are shorted or the reliability is reduced in the memory device 3.

[0067]

Thus, the stopper film 40S prevents the etching of the inter-layer insulating film 15T and the sacrificial films 17 in the process of forming the memory hole MH2, and increases the manufacturing yield and the reliability of the memory device 3. The stopper film 40S includes a material that is resistant to the etching conditions under which the sacrificial films 27 is selectively removed. In other words, it is desirable for the stopper film 40S not to be etched in the process of replacing the sacrificial films 27 with the word lines WL2.

[0068]

FIG. 16 is a schematic cross-sectional view showing a memory device 4 according to a modification of the second embodiment. The cross-sectional structure of the columnar bodies PB1 and PB2 is shown in FIG. 16.

[0069]

As shown in FIG. 16, the columnar body PB1 extends in the Z-direction through the select gate SGS and the multiple

word lines WL1. The columnar body PB2 extends in the Z-direction through the multiple word lines WL2 and the select gate SGD. The columnar body PB1 and the columnar body PB2 are connected between the word line WLT1 and the word line WLL2.
5 The stopper film 40S is provided to surround the upper end of the columnar body PB1.

[0070]

In the example, the word line WLL2 is provided at a position apart from the stopper film 40S. For example, the inter-layer
10 insulating film 25 is provided between the word line WLL2 and the stopper film 40S and between the word line WLL2 and the insulating film 43.

Such a structure is formed by, for example, stacking a sacrificial film 27 (referring to FIGS. 14A and 14B) after an inter-layer
15 insulating film 25 is formed on the insulating film 43. Thereby, it is possible to prevent the stopper film 40S from the etching in the process of replacing the sacrificial films 27 with the word lines WL2. The stopper film 40S can include, for example, the same material as the sacrificial film 27. In the example, when
20 the sacrificial film 27 includes silicon nitride, the stopper film 40S can include silicon nitride (SiN). Moreover, polysilicon or amorphous silicon with an impurity added may be used as the material of the stopper film 40S, because the stopper film 40S is electrically insulated from the word line WLL2 by the inter-layer
25 insulating film 25.

[0071]

(Third embodiment)

FIG. 17 is a schematic cross-sectional view showing a memory device 5 according to a third embodiment. The cross-sectional structure of the columnar bodies PB1 and PB2 is shown
30 in FIG. 17.

[0072]

As shown in FIG. 17, the columnar body PB1 extends in the Z-direction through the select gate SGS and the multiple word
35 lines WL1. The columnar body PB2 extends in the Z-direction through the multiple word lines WL2 and the select

gate SGD. The columnar body PB1 and the columnar body PB2 are connected between the word line WLT1 and the word line WLL2.

[0073]

5 In the example, the connection part JP is provided between the word line WLT1 and the word line WLL2. The connection part JP includes an enlarged portion MFJ of the memory film MF, an enlarged portion SFJ of the semiconductor film SF, and an enlarged portion CAJ of the insulating core CA.
10 For example, the connection part JP has a structure in which the upper end of the columnar body PB1 is enlarged in the X-direction and the Y-direction. For example, the connection part JP is positioned between the inter-layer insulating film 15T and the word line WLL2.

15 [0074]

For example, the connection part JP is surrounded with the insulating film 43 in a cross section parallel to the upper surface of the word line WLT1 or the lower surface of the word line WLL2. Also, for example, the connection part JP has a
20 configuration in which the thickness in the Z-direction of a portion positioned inward is greater than the thickness in the Z-direction of a portion positioned at the outer edge. The connection part JP has a lower surface contacting the inter-layer insulating film 15T. In the connection part JP, the width in the
25 X-direction or the Y-direction of the lower surface is greater than the width in the X-direction or the Y-direction at a portion proximate to the word line WLL2.

[0075]

A method for manufacturing the memory device 5
30 according to the third embodiment will now be described with reference to FIGS. 18A to 19B. FIGS. 18A to 19B are schematic cross-sectional views showing manufacturing processes of the memory device 5 in order.

[0076]

35 As shown in FIG. 18A, the multiple sacrificial films 17 are stacked on the source layer SL with the inter-layer insulating

films 13 and 15 interposed. Then, the memory hole MH1 is formed with a depth reaching the source layer SL from the surface of the inter-layer insulating film 25T at the top position. Subsequently, the sacrificial film 33 that fills the interior of the memory hole MH1 is formed. As a result, the sacrificial film 33 is provided to extend in the Z-direction through the inter-layer insulating films 13 and 15 and the sacrificial film 17 stacked on the source layer SL.

[0077]

Also, a portion of the sacrificial film 33 and a portion of the inter-layer insulating film 15T are removed so that the upper end of the sacrificial film 33 protrudes to a higher level than the inter-layer insulating film 15T. Then, a sacrificial film 50 is formed on the inter-layer insulating film 15T. The sacrificial film 50 is, for example, an amorphous silicon film formed using CVD and covers the upper end of the sacrificial film 33. For example, the sacrificial film 50 has a thickness in the Z-direction that is about the same as the width in the Z-direction of the portion of the sacrificial film 33 protruding to the higher level than the inter-layer insulating film 15T.

[0078]

As shown in FIG. 18B, the sacrificial film 50 is etched back so that the portion thereof surrounding the upper end of the sacrificial film 33 remains. For example, the sacrificial film 50 is etched back using anisotropic RIE. Thereby, a sacrificial film 50S is formed around the upper end of the sacrificial film 33.

[0079]

As shown in FIG. 18C, the insulating film 43 is formed on the inter-layer insulating film 15T. The insulating film 43 is formed so that the upper surface of the sacrificial film 33 is exposed to the outside. For example, the insulating film 43 is partially removed using CMP or is subjected to etch-back after the insulating film 43 is formed to cover the sacrificial film 33 and the sacrificial film 50S by using CVD. The surface of the insulating film 43 is planarized in which the upper surface of the

sacrificial film 33 is exposed.

[0080]

As shown in FIG. 19A, the multiple sacrificial films 27 are stacked on the insulating film 43 with the inter-layer insulating films 25 interposed. The inter-layer insulating film 25 and the sacrificial film 27 are alternately stacked on the insulating film 43. Subsequently, the memory hole MH2 is formed from the surface of the inter-layer insulating film 25T at the top position so that the memory hole MH2 is in communication with the sacrificial film 33.

[0081]

The sacrificial film 50S protects the inter-layer insulating film 15T and the sacrificial films 17 provided below the sacrificial film 50S in the process of forming the memory hole MH2. Thereby, the etching of the inter-layer insulating film 15T and the sacrificial films 17 can be prevented when the bottom surface of the memory hole MH2 is shifted from a position matching the upper surface of the sacrificial film 33 due to the misalignment of the memory hole MH2 (referring to FIG. 15B).

[0082]

As shown in FIG. 19B, the memory hole MH is formed with a depth reaching the source layer SL from the upper surface of the inter-layer insulating film 25T. For example, the memory hole MH is formed by selectively removing the sacrificial film 33. The memory hole MH includes an enlarged region 50F between the inter-layer insulating film 15T and the sacrificial film 27 at the bottom position. The enlarged region 50F is formed by selectively removing the sacrificial film 50S simultaneously with the sacrificial film 33.

[0083]

Continuing, the memory film MF, the semiconductor film SF, and the insulating core CA are formed inside the memory hole MH. The memory film MF includes the enlarged portion MFJ formed along the inner surface of the enlarged region 50F of the memory hole MH. The semiconductor film SF includes

the enlarged portion SFJ formed on the enlarged portion MFJ of the memory film MF. The insulating core CA includes the enlarged portion CAJ that fills the space in the enlarged region 50F. Also, the word lines WL1 and WL2 and the select gates
5 SGS and SGD are formed by selectively removing the sacrificial films 17 and 25 and replacing the sacrificial films 17 and 25 with metal layers.

[0084]

In the embodiment, by providing the connection part JP
10 including the enlarged portions MFJ, SFJ, and CAJ, the manufacturing yield can be increased and the reliability is improved in the memory device 5.

[0085]

(Fourth embodiment)

15 FIG. 20 is a schematic cross-sectional view showing a memory device 6 according to a fourth embodiment. FIG. 20 shows a cross section of a stacked body including the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD. The cross section shown in FIG. 20 includes
20 the cross section of a columnar body PB.

[0086]

As shown in FIG. 20, the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD are stacked on the source layer SL with the inter-layer insulating films 13,
25 15, and 25 interposed. Multiple stacked bodies that include the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD are provided and arranged in, for example, the X-direction. The stacked bodies are separated from each other by a slit ST. For example, a connection conductor LI is
30 provided inside the slit ST. The connection conductor LI is electrically insulated from the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD by an insulating film 55 covering the inner wall of the slit ST. Also, the connection conductor LI is electrically connected to the
35 source layer SL. The source layer SL is connected to a control circuit (not illustrated) via the connection conductor LI.

[0087]

The columnar body PB extends in the Z-direction through the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD. The columnar body PB includes, for example,
5 the memory film MF, the semiconductor film SF, and the insulating core. The columnar body PB includes the columnar body PB1 and the columnar body PB2. The columnar body PB1 extends in the Z-direction through the select gate SGS and the multiple word lines WL1. The columnar body PB2 extends in the Z-direction through
10 the multiple word lines WL2 and the select gate SGD. The columnar body PB1 and the columnar body PB2 are connected between the word line WLT1 and the word line WLL2.

[0088]

In the example, a stopper film 60S is provided between the
15 word line WLT1 and the word line WLL2. For example, the stopper film 60S is selectively provided in the region where the multiple columnar bodies PB are disposed. The columnar bodies PB are provided to extend through the stopper film 60S. For example, the stopper film 60S is not provided in the region where contact
20 plugs (not illustrated) that connect the word lines WL1 and WL2 to a control circuit (not illustrated) are disposed, nor in the region divided by the slit ST.

[0089]

The stopper film 60S can include a metal oxide such as
25 aluminum oxide (Al_2O_3), hafnium oxide (HfO), tungsten oxide (WO_x), titanium oxide (TiO), etc. Also, the stopper film 60S can include, for example, silicon nitride (SiN) or silicon carbide (SiC). When the inter-layer insulating film 15T and the insulating film 43 are not silicon oxide films, the stopper film 60S may include
30 silicon oxide (SiO_2).

[0090]

A method for manufacturing the memory device 6 according to the fourth embodiment will now be described with reference to FIGS. 21A to 22B. FIGS. 21A to 22B are schematic cross-
35 sectional views showing manufacturing

processes of the memory device 6 according to the fourth embodiment in order.

[0091]

As shown in FIG. 21A, the sacrificial film 33 extends in
5 the Z-direction and extends through the sacrificial films 17
stacked on the source layer SL with the inter-layer insulating
films 13 and 15 interposed. The sacrificial film 33 is provided
so that the upper end of the sacrificial film 33 protrudes to a
higher level than the inter-layer insulating film 15T. Then, a
10 stopper film 60 is formed on the inter-layer insulating film 15T.
The stopper film 60 is formed to cover the upper end of the
sacrificial film 33.

[0092]

The stopper film 60 includes a stopper film 60M and a
15 stopper film 60P. The stopper film 60 M is formed in the region
where the multiple sacrificial films 33 are provided; and the
stopper film 60P is provided at the periphery of the region.
For example, the thickness in the Z-direction of the stopper film
60M is greater than the thickness in the Z-direction of the
20 stopper film 60P. For example, after forming the stopper film
60 on the insulating film 43 with a uniform thickness, the
stopper film 60P is formed by selectively thinning the stopper
film 60 at the region other than the portion where the sacrificial
films 33 are provided.

25 [0093]

As shown in FIG. 21B, the stopper film 60 is etched back
so that the portion thereof remains at the region where the
sacrificial films 33 are provided. For example, the stopper film
60 is etched back using RIE. Thereby, the stopper film 60S is
30 formed around the upper ends of the sacrificial films 33. The
stopper film 60S is formed to cover the region where the
multiple sacrificial films 33 are formed so that the upper
surfaces of the sacrificial films 33 are exposed at the surface of
the stopper film 60S.

35 [0094]

As shown in FIG. 21C, the insulating film 43 is formed on

the inter-layer insulating film 15T. The insulating film 43 is formed so that the upper surfaces of the sacrificial films 33 and the upper surface of the stopper film 60S are exposed. For example, the insulating film 43 is partially removed using CMP or subjected to etch-back after being formed to cover the sacrificial film 33 and the stopper film 60S by using CVD. The surface of the insulating film 43 is planarized in which the upper surfaces of the sacrificial films 33 and the upper surface of the stopper film 60S are exposed.

10 [0095]

As shown in FIG. 22A, the multiple sacrificial films 27 are stacked on the sacrificial film 33, the stopper film 60S, and the insulating film 43 with the inter-layer insulating films 25 interposed. The inter-layer insulating film 25 and the sacrificial film 27 are alternately stacked. Subsequently, the memory hole MH2 is formed from the surface of the inter-layer insulating film 25T at the top position so that the memory hole MH2 communicates with the sacrificial film 33.

[0096]

20 The stopper film 60S protects the inter-layer insulating film 15T and the sacrificial films 17 provided below the stopper film 60S in the process of forming the memory hole MH2. Thereby, the inter-layer insulating film 15T and the sacrificial films 17 can be prevented from being etched when the bottom surface of the memory hole MH2 is shifted from a position matching the upper surface of the sacrificial film 33 due to the misalignment of the memory hole MH2 (referring to FIG. 15B).

[0097]

30 As shown in FIG. 22B, the memory hole MH is formed with a depth reaching the source layer SL from the upper surface of the inter-layer insulating film 25T. For example, the memory hole MH is formed by selectively removing the sacrificial film 33.

[0098]

35 Continuing, the memory film MF, the semiconductor film SF, and the insulating core CA are formed inside the memory

hole MH. Also, the word lines WL1 and WL2 and the select gates SGS and SGD are formed by selectively removing the sacrificial films 17 and 25 and replacing the sacrificial films 17 and 25 with metal layers.

5 [0099]

FIG. 23 is a schematic cross-sectional view showing a memory device 7 according to a modification of the fourth embodiment. FIG. 23 shows a cross-sectional structure of a stacked body including the select gate SGS, the word lines WL1,
10 the word lines WL2, and the select gate SGD. The cross section of the columnar body PB also is illustrated in FIG. 23.

[0100]

As shown in FIG. 23, the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD are stacked
15 on the source layer SL with the inter-layer insulating films 13, 15, and 25 interposed. Multiple stacked bodies including the select gate SGS, the word lines WL1, the word lines WL2 and the select gate SGD are provided and arranged in, for example, the X-direction. The stacked bodies are separated from each
20 other by the slit ST. For example, the connection conductor LI is provided inside the slit ST. The connection conductor LI is electrically insulated from the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD by the insulating film 55 covering the inner wall of the slit ST.
25 Moreover, the connection conductor LI is electrically connected to the source layer SL. The source layer SL is connected to the control circuit via the connection conductor LI.

[0101]

The columnar body PB extends in the Z-direction through
30 the select gate SGS, the word lines WL1, the word lines WL2, and the select gate SGD. The columnar body PB includes, for example, the memory film MF, the semiconductor film SF, and the insulating core. The columnar body PB includes the columnar body PB1 and the columnar body PB2. The columnar
35 body PB1 extends in the Z-direction through the select gate SGS and the multiple word lines WL1. The columnar body PB2

extends in the Z-direction through the multiple word lines WL2 and the select gate SGD. The columnar body PB1 and the columnar body PB2 are connected between the word line WLT1 and the word line WLL2.

5 [0102]

In the example, a stopper film 70S is provided between the word line WLT1 and the word line WLL2. For example, the stopper film 70S is selectively provided in the region where the multiple columnar bodies PB are disposed. The columnar body
10 PB is provided to extend through the stopper film 70S. The stopper film 70S includes, for example, a recess 70D positioned between adjacent columnar bodies PB.

[0103]

The stopper film 70S can include a metal oxide such as
15 aluminum oxide (Al_2O_3), hafnium oxide (HfO), tungsten oxide (WO_x), titanium oxide (TiO), etc. Also, the stopper film 70S may include a semiconductor such as polysilicon or amorphous silicon doped with an impurity. Also, the stopper film 70S can include, for example, silicon nitride (SiN) or silicon carbide (SiC).
20 When the inter-layer insulating film 15T and the insulating film 43 are not silicon oxide films, the stopper film 70S may include silicon oxide (SiO_2).

[0104]

A method for manufacturing the memory device 7
25 according to the modification of the fourth embodiment will now be described with reference to FIGS. 24A to 26B. FIGS. 24A to 26B are schematic views showing manufacturing processes of the memory device 7 in order. FIGS. 24A to 24C and FIGS. 26A and 26B are cross-sectional views showing a cross section
30 along line K-K shown in FIG. 25. FIG. 25 is a plan view.

[0105]

As shown in FIG. 24A, the sacrificial film 33 extends in the Z-direction and extends through the multiple sacrificial films 17 stacked on the source layer SL with the inter-layer insulating
35 films 13 and 15 interposed. The sacrificial film 33 is provided so that the upper end of the sacrificial film 33 protrudes to a

higher level than the inter-layer insulating film 15T. Then, a stopper film 70 is formed on the inter-layer insulating film 15T. The stopper film 70 is formed to cover the upper end of the sacrificial film 33.

5 [0106]

The stopper film 70 includes a portion 70m positioned between the sacrificial films 33 and a portion 70f positioned at a region where the sacrificial film 33 is not provided. For example, when the spacing between the adjacent sacrificial
10 films 33 is narrow, the stopper film 70 is formed so that the thickness in the Z-direction of a portion 70m is greater than the thickness in the Z-direction of a portion 70f.

[0107]

As shown in FIG. 24B, the stopper film 70 is etched back
15 so that a portion thereof remains at the region where the multiple sacrificial films 33 are provided. For example, the stopper film 70 is etched back using RIE. Thereby, the stopper film 70S is formed around the upper ends of the sacrificial films 33. The stopper film 70S is formed to cover the region where
20 the sacrificial films 33 are formed so that the upper surfaces of the sacrificial films 33 are exposed at the surface of the stopper film 70S. Also, the stopper film 70S includes the recess 70D positioned between the adjacent sacrificial films 33.

[0108]

25 As shown in FIG. 24C, the insulating film 43 is formed on the inter-layer insulating film 15T. The insulating film 43 is formed so that the upper surfaces of the sacrificial films 33 and the upper surface of the stopper film 70S are exposed. For example, the insulating film 43 is partially removed using CMP
30 or subjected to etch-back after being formed to cover the sacrificial films 33 and the stopper film 70S by using CVD. The surface of the insulating film 43 is planarized in which the upper surfaces of the sacrificial films 33 and the upper surface of the stopper film 60S are exposed.

35 [0109]

FIG. 25 is a schematic plan view showing the surface of

the insulating film 43. As shown in the drawing, the insulating film 43 is formed to surround the region where the sacrificial films 33 are provided. Moreover, the insulating film 43 includes a portion formed inside the recess 70D positioned
5 between the adjacent sacrificial films 33.

[0110]

As shown in FIG. 25, for example, the stopper film 70S is not formed in the region where the slit ST is provided. Also, the stopper film 70S is not formed at both sides in the
10 Y-direction of the region where the multiple sacrificial films 33 are provided. For example, the contact plugs that are connected to the word lines WL1 are provided in this region.

[0111]

As shown in FIG. 26A, the multiple sacrificial films 27 are
15 stacked on the sacrificial film 33, the stopper film 70S and the insulating film 43 with the inter-layer insulating films 25 interposed. The inter-layer insulating film 25 and the sacrificial film 27 are alternately stacked. Subsequently, the memory hole MH2 is formed from the surface of the inter-layer
20 insulating film 25T at the top position so that the memory hole MH2 communicates with the sacrificial film 33. Although, in the example, the inter-layer insulating film 25 is formed between the stopper film 70S and a sacrificial film 27L at the bottom position, the sacrificial film 27L may be provided in the
25 structure in which the sacrificial film 27L contacts the stopper film 70S.

[0112]

The stopper film 70S protects the inter-layer insulating film 15T and the sacrificial films 17 provided below the stopper
30 film 70S in the process of forming the memory hole MH2. Thereby, the inter-layer insulating film 15T and the sacrificial films 17 can be prevented from being etched when the bottom surface of the memory hole MH2 is shifted from a position matching the upper surface of the sacrificial film 33 due to the
35 misalignment of the memory hole MH2 (referring to FIG. 15B).

[0113]

As shown in FIG. 26B, the memory hole MH is formed with a depth reaching the source layer SL from the upper surface of the inter-layer insulating film 25T. The memory hole MH is formed by, for example, selectively removing the
5 sacrificial film 33.

[0114]

Continuing, the memory film MF, the semiconductor film SF, and the insulating core CA are formed inside the memory hole MH. Also, the word lines WL1 and WL2 and the select
10 gates SGS and SGD are formed by selectively removing the sacrificial films 17 and 25 and replacing the sacrificial films 17 and 25 with metal layers.

[0115]

FIG. 27 is a schematic cross-sectional view showing a
15 manufacturing process of the memory device 7 according to the modification of the fourth embodiment. In the example, after forming the memory hole MH shown in FIG. 26B, a portion 70X is removed in the stopper film 70S.

[0116]

For example, after forming the memory hole MH2, the
20 stopper film 70S is partially exposed at the bottom surface of the memory hole MH2 (referring to FIG. 26A). Therefore, the portion 70X of the stopper film 70 protruding from the inner wall of the memory hole MH remains after the sacrificial film 33
25 is selectively removed. For example, the portion 70X of the stopper film 70 is removed using anisotropic RIE.

[0117]

In the example, it is possible to form the memory film MF and the semiconductor film SF on the inner surface of the
30 memory hole MH with a uniform thickness over the region where the portion 70X of the stopper film 70 is removed. Moreover, by reducing the length in the vertical direction of the semiconductor film SF in the connection region between the columnar body PB2 and the columnar body PB1, the channel
35 current flowing in the Z-direction can be prevented from decreasing.

[0118]

FIG. 28 is a schematic plan view showing a memory device 8 according to another modification of the fourth embodiment. FIG. 28 is a plan view corresponding to FIG. 25 and illustrates the surface of the insulating film 43.

[0119]

As shown in FIG. 28, the sacrificial films 33 and sacrificial films 37 are provided in the manufacturing processes of the memory device 8. The sacrificial films 33 and 37 extend in the Z-direction and extend through the sacrificial films 17 stacked on the source layer SL with the inter-layer insulating films 13 and 15 interposed. For example, the sacrificial films 33 are formed in the region where the columnar bodies PB are provided. The sacrificial films 37 are provided, for example, in the region where contact plugs CC are provided. For example, the sacrificial films 37 are replaced with columnar support bodies (not illustrated). For example, the columnar support bodies support the inter-layer insulating films 15 in the process of forming the word lines WL1 and the select gate SGD by replacing the sacrificial films 17 with the metal layers. The columnar support bodies are provided to maintain the space that remains after the sacrificial films 17 are selectively removed.

[0120]

In the example, stopper films 70G surrounding the sacrificial films 37 are provided in addition to the stopper film 70S. For example, the stopper films 70G are provided to surround the columnar support bodies (not illustrated) between the word line WLT1 and the word line WLL2. The stopper films 70G are provided around the multiple columnar support bodies and are separated from each other.

[0121]

The examples described in the first to fourth embodiments are not limited to the aspects described in the examples. For example, structural elements having the same reference numerals are common between the embodiments,

and a structural element described in one embodiment is applicable also to the other embodiments if technically possible.

[0122]

While certain embodiments have been described, these
 5 embodiments have been presented by way of example only, and
 are not intended to limit the scope of the inventions. Indeed,
 the novel embodiments described herein may be embodied in a
 variety of other forms; furthermore, various omissions,
 substitutions and changes in the form of the embodiments
 10 described herein may be made without departing from the spirit
 of the inventions. The accompanying claims and their
 equivalents are intended to cover such forms or modifications
 as would fall within the scope and spirit of the invention.
 [Reference Numeral List]

15 [0123]

1 to 8 memory devices; 13, 15, 15T, 23, 25, 25T inter-layer
 insulating films; 17, 17B, 17T, 27, 27L, 33, 35, 37, 50, 50S
 sacrificial films; 20 spacer film; 40, 40S, 60, 60M, 60P, 60S,
 70, 70G, 70S stopper films; 43, 55 insulating films; 50F
 20 enlarged region; 70D recess; BL bit line; CA insulating core;
 CAJ enlarged portion; CC contact plug; FL1 blocking
 insulating film; FL2 charge storage film; FL3 tunnel insulating
 film; JP connection part; LI connection conductor; MC
 memory cell; MF memory film; MFJ enlarged portion; MH,
 25 MH1, MH2 memory holes; PB, PB1, PB2 columnar bodies; RC
 recess portion; SF semiconductor film; SFJ enlarged portion;
 SGD, SGS select gates; SL source layer; ST slit; VB
 connection plug; WL, WL1, WLT1, WL2, WLL2 word lines

What is claimed is:

[Claim 1]

A semiconductor memory device, comprising:

5 a plurality of first electrode layers stacked in a first direction;

a first insulating film provided above an uppermost layer of the plurality of first electrode layers;

a plurality of second electrode layers stacked in the first direction and provided above the first insulating film;

10 a first columnar body extending through the plurality of first electrode layers in the first direction and including a first charge storage film;

a second columnar body extending through the plurality of second electrode layers in the first direction and including a second charge storage film;

15 a connection part connecting the first columnar body and the second columnar body, the connection part being provided in the first insulating film and including a third charge storage film, the first to third charge storage films being continuously provided in the first and second columnar bodies and the connection part, the connection part including a first portion having minimum and maximum widths in a second direction crossing the first direction; and

20 a spacer film provided around the first portion of the connection part and positioned between the first insulating film and the first portion of the connection part,

the first columnar body including a second portion facing the uppermost layer of the plurality of first electrode layers, the second portion of the first columnar body having a first width in the second direction, the first width of the second portion in the first columnar body being greater than the minimum width of the first portion in the connection part,

the second columnar body including a third portion facing a lowermost layer of the plurality of second electrode layers, the third portion of the second columnar body having a second width in the second direction, the second width of the third portion in the second columnar body being less than the maximum width of the first portion in the connection part.

[Claim 2]

The semiconductor memory device according to claim 1,
10 wherein

the first columnar body has a substantially circular configuration in a cross-section orthogonal to the first direction; and

the first columnar body has a center in the cross-section orthogonal to the first direction, the center of the first columnar body
15 being substantially aligned with a center of the spacer film in a cross section orthogonal to the first direction.

[Claim 3]

The semiconductor memory device according to claim 1,
20 wherein

the plurality of first electrode layers includes a first electrode layer provided at the furthest position from the connection part; and

the first columnar body includes a fourth portion extending through the first electrode layer of the plurality of first electrode
25 layers, the fourth portion of the first columnar body having a third width in the second direction, the third width being greater than the minimum width of the connection part.

[Claim 4]

30 The semiconductor memory device according to claim 1, wherein the second width of the third portion in the second columnar

body is less than the first width of the second portion in the first columnar body.

[Claim 5]

5 The semiconductor memory device according to claim 1, wherein

 the first columnar body and the connection part include an insulating core and a semiconductor film, the insulating core extending in the first direction, the semiconductor film surrounding
10 the insulating core and extending in the first direction; and

 the semiconductor film has an outer diameter at the first columnar body and another outer diameter at the connection part, the outer diameter at the first columnar body being greater than a minimum value of said another outer diameter at the connection part.

15

[Claim 6]

 The semiconductor memory device according to claim 1, wherein

 the first portion of the connection part has the minimum width
20 at the first columnar body side, and the maximum width at the second columnar body side.